Demonstration Equipment Example

Field	Model	Process	Workpiece size / Furnace internal dimensions / Belt width (mm)	Temperature
Semiconductor	VF-1000HLP	Activated annealing, High temperature H2 annealing, Vacuum purge available	Up to φ200mm	800 to 1800℃
	VF-5300H	Annealing, Oxidation (Dry, Pyrogenic)	Up to φ200mm	700 to 1350℃
	VF-5100LP	LP-CVD（Poly-Si, Si3N4, HTO）	Up to φ200mm	600 to 850℃
	VF-3000	Annealing, Oxidation (Dry, Wet (Bubbling)), Low-temperature wet oxidation for VCSEL	Up to φ200mm	200 to 1100℃
	VF-1000	Annealing, Oxidation (Dry, Wet (Vaporizer)), Low-temperature wet oxidation for VCSEL, Vacuum purge available	Up to φ300mm	200 to 1100℃
	VF-1000B	Low-temperature wet oxidation for VCSEL (wet (vaporizer))	Up to φ150mm	200 to 600℃
	VF-5700B	Low temperature annealing, PIQ	Up to φ300mm	200 to 750℃
	RLA-1208-V	Annealing, Oxidation (Dry)	Up to φ200mm	600 to 1200℃
PV (Photovoltaic)	206A-M100	Annealing, POCl3	156x156mm	400 to 1100℃
FPD	CCBS-IR	Various heat treatments for flat panel displays	300(W)×400(L) to 3000(W)×3200(L)	RT to 250℃
Electronic component	AF-INH21	Debinding of electronic and ceramic components, metal components, and other products, Degreasing, Drying, Other heat treatment of products where it was not possible to increase heating efficiency with other conventional methods	Furnace internal dimensions: 600(W)×600(H)×600(D)	RT+60 to 600℃
	AF-INH100		Furnace internal dimensions: 1000(W)×1000(H)×1000(D)	
	AF-μBF		Effective dimensions:200(W)×200(H)×400(D)	400 to 900℃
	AF-810A	Debinding of electronic and ceramic components, metal components, and other products, Degreasing, Drying, Firing Other heat treatment of products where it was not possible to increase heating efficiency with other conventional methods	Belt width：200	250 to 900℃
	Mesh Belt Type Continuous Furnace Multi-Inlet/Exhaust Type	Various heat treatments for electronic components and other products	Belt width：350	～950℃
	Mesh Belt Type Continuous Furnace Compact Conveyor Furnace 810A-II	Various heat treatments for electronic components and other products	Belt width：200	～1000℃
	Ceramic Conveyor Type Continuous Furnace	Various heat treatments for electronic components and other products	Treatable workpiece sizes: Up to 200(W)×75(H)	～1400℃
	High-Temperature Inert Gas Oven INH-21CD	Debinding of electronic and ceramic components, metal components, and other products, Degreasing, Drying, Various other heat treatments	Furnace internal dimensions: 600(W)×600(H)×600(D)	RT+60 to 600℃
	High-Temperature Inert Gas Oven INH-51N2-DBS		Furnace internal dimensions: 800(W)×800(H)×800(D)	RT+60 to 600℃
	High-Temperature Clean Oven CLH-21CD(V)	Baking, curing, and aging for semiconductor wafers and glass substrates, Various heat treatment for electronic components and other products	Furnace internal dimensions: 700(W)×700(H)×500(D) * Opening size is 630 mm.	RT＋70～500℃